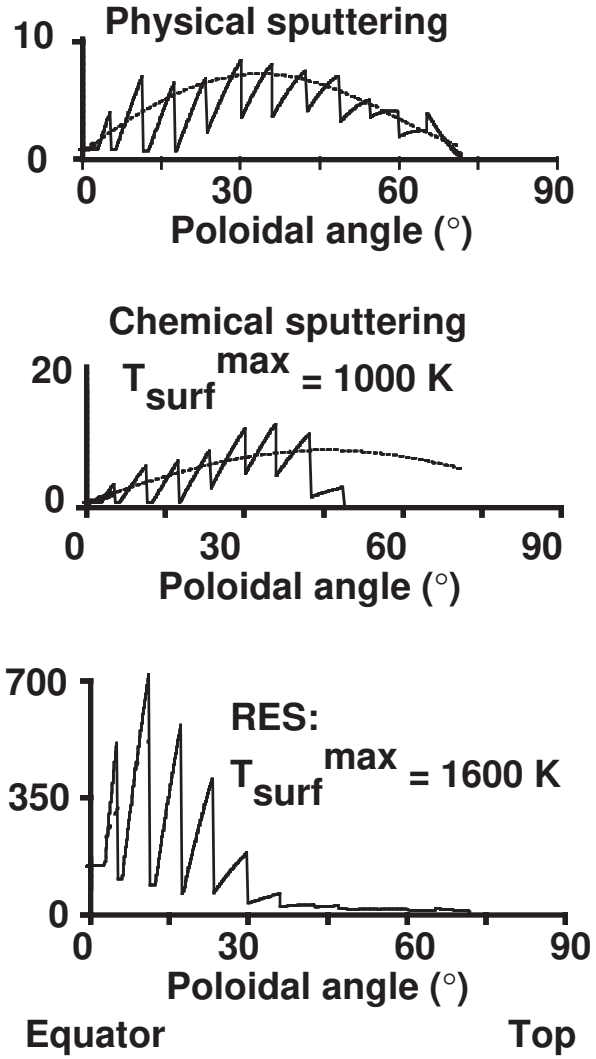

FIG. 4
Calculated local effective sputtering yield distributions (emitted impurity flux / incident D+ flux, %) for (top) physical sputtering, (middle) chemical sputtering (T_{wall}^{max} = 1000K) and (bottom) RES (T_{wall}^{max} = 1600K)